



Product Change Notification

107206 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 107206 - 00
Change Title: Intel® Optical Transceiver, TXN174310850, PCN 107206-00, Product Material, Product Material, Addition of Second Source PCB and Optics Vendor Related Changes
Date of Publication: January 17, 2007

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date of Qualification Data Availability:	Jan 19, 2007
Date Customer Must be Ready to Receive Post-Conversion Material:	Feb 19, 2007

Description of Change to the Customer:

The Intel® TXN174310850 Optical Transceiver uses TTM Printed Circuit Board (PCB). In order to improve supply, Intel will qualify a second source for PCB used in TXN174310850. Merix PCB will be used as the second sources for TXN174310850.

Intel will use the EEPROM Byte x80C5 to track PCB type in production. The Byte will contain the following values depending on the PCB type. Intel will continue to ship from both PCB vendors and this change will be transparent to the customers.

EEPROM (x80C5)	TOSA	ROSA	PCB
0	AOC	AOC	TTM
1	AOC	AOC	Merix

In addition to qualifying the second source PCB, Intel will also improve the optical eye mask margin for TXN174310850 by changing the values of a few passive components such as resistors and capacitors in the drive chain of the transmitter.

Optics Vendor Related Changes

The Intel® TXN174310850 Optical Transceiver uses Advanced Optical Components (AOC) Transmitter Optical Sub-Assembly (TOSA), AOC Receiver Optical Sub-Assembly (ROSA) and AOC is implementing a few changes on the TOSA and ROSA used for TXN174310850. The changes are described in detail below.

TOSA

1. Header Glass and Pins: AOC will change the high speed glass used in the header to brown glass to improve reliability. They will also change 2 small pins in the header to have nail heads, giving a much larger area to wirebond.
2. VCSEL Resistance: AOC will change the minimum VCSEL resistance from 45ohms to 41ohms to improve supply.
3. TO Can: AOC will change the TO can from tapered wall to straight (cylindrical) wall to eliminate mechanical shift in barrel.
4. Gold pads: AOC will increase the gold pad size on the ceramic spacer to allow more room for die attach and wirebonding.

ROSA

1. Header Glass and Pins: AOC will change the high speed glass used in the header to brown glass to improve reliability. They will also change 2 small pins in the header to nail heads which gives a much larger area to wirebond.
2. Move of Assembly Line: AOC will move ROSA connectorizing and testing from Allen, Texas to Fabrinet, Thailand to improve supply. TO can packaging will remain at Allen, Texas

Customer Impact of Change and Recommended Action:

Intel has performed full quality and reliability including 1000 hours testing and complete design verification testing for TXN174310850 to ensure that there is no quality, reliability or functional implications to our customers. The qualification reports for TXN174310850 will be available in Jan 2007. Please contact your local Intel sales representative to request the qualification reports.

First samples of the TXN174310850 with second source PCB and optics vendor related changes will be available in Jan 2007. General production availability for the TXN174310850 with second source and optics vendor related changes will be in Feb 2007.

Intel will change the Top Assembly number (TA#) for TXN174310850 with second source PCB and optics vendor related changes. Please use the chart below for the updated TA# that will be used for TXN174310850 with second source PCB and optics vendor related changes.

Products Affected / Intel Ordering Codes:

Affected Product Code	Affected MM#	Pre-Change TA#	Post-Change TA#
TXN174310850F16	872628	D27613-003	D27613-004
TXN174310850F1B	872633	D38011-002	D38011-003
TXN174310850F1C	872629	D30832-003	D30832-004
TXN174310850F1G	884629	D70412-002	D70412-003

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

Revision Number:

Reason:

January 17, 2007

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Originally Published PCN